

# CMOS Static RAM 256K (32K x 8-Bit)

#### Features

- 32K x 8 advanced high-speed CMOS static RAM
- Commercial (0° to 70°C) and Industrial (-40° to 85°C) temperature options
- Equal access and cycle times

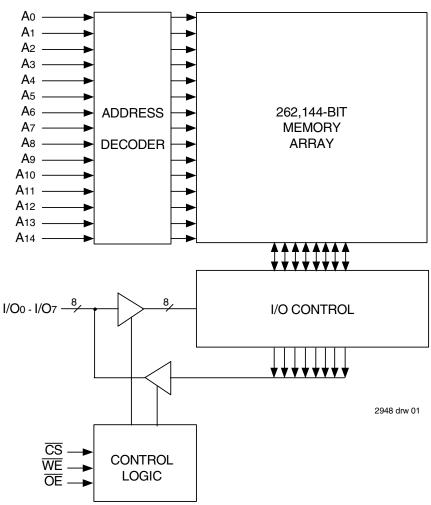
   Commercial and Industrial: 12/15/20/25ns
- One Chip Select plus one Output Enable pin
- Bidirectional data inputs and outputs directly TTL-compatible
- Low power consumption via chip deselect
- Commercial product available in 28-pin 300-mil Plastic DIP, 300 mil Plastic SOJ and TSOP packages
- Industrial product available in 28-pin 300 mil Plastic SOJ and TSOP packages

#### Description

The IDT71256SA is a 262,144-bit high-speed Static RAM organized as 32K x 8. It is fabricated using IDT's high-perfomance, high-reliability CMOS technology. This state-of-the-art technology, combined with innovative circuit design techniques, provides a cost-effective solution for high-speed memory needs.

The IDT71256SA has an output enable pin which operates as fast as 6ns, with address access times as fast as 12ns. All bidirectional inputs and outputs of the IDT71256SA are TTL-compatible and operation is from a single 5V supply. Fully static asynchronous circuitry is used, requiring no clocks or refresh for operation.

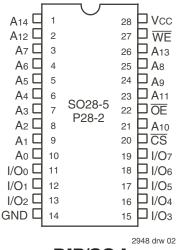
The IDT71256SA is packaged in 28-pin 300-mil Plastic DIP, 28-pin 300 mil Plastic SOJ and TSOP.



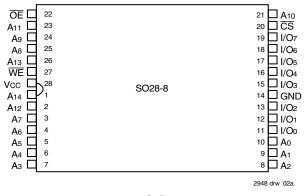
### **Functional Block Diagram**

#### **APRIL 2011**

#### **Pin Configurations**



DIP/SOJ Top View



TSOP Top View Commercial and Industrial Temperature Ranges

#### Absolute Maximum Ratings<sup>(1)</sup>

Symbol	Rating	Value	Unit
Vcc	Supply Voltage Relative to GND	-0.5 to +7.0	V
VTERM	Terminal Voltage Relative to GND	-0.5 to Vcc+0.5	V
TBIAS	Temperature Under Bias	-55 to +125	°C
Tstg	Storage Temperature	-55 to +125	°C
Рт	Power Dissipation	1.0	W
Ιουτ	DC Output Current	50	mA

NOTE:

 Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

#### Truth Table<sup>(1,2)</sup>

		_		
<u>C</u> S	ŌĒ	WE	I/O	Function
L	L	Н	DATAOUT	Read Data
L	Х	L	DATAIN	Write Data
L	Н	Н	High-Z	Outputs Disabled
Н	Х	Х	High-Z	Deselected - Standby (IsB)
VHC <sup>(3)</sup>	Х	Х	High-Z	Deselected - Standby (ISB1)
NOTEO				2948 tbl 03

NOTES:

1.  $H = V_{IH}$ ,  $L = V_{IL}$ , x = Don't care.

2.  $V_{LC} = 0.2V$ ,  $V_{HC} = V_{CC} - 0.2V$ .

3. Other inputs  $\geq$ VHC or  $\leq$ VLC.

#### **Recommended Operating Temperature and Supply Voltage**

Grade	Temperature	GND	Vcc
Commercial	0°C to +70°C	0V	4.5V ± 5.5V
Industrial	-40°C to +85°C	0V	4.5V ± 5.5V

2948 tbl 01

#### **Recommended DC Operating** Conditions

Symbol	Parameter	Min.	Тур.	Max.	Unit
Vcc	Supply Voltage	4.5	5.0	5.5	۷
GND	Ground	0	0	0	۷
V⊮	Input High Voltage	2.2		Vcc +0.5	۷
Vil	Input Low Voltage	-0.5 <sup>(1)</sup>		0.8	۷

NOTE:

1. VL (min.) = -1.5V for pulse width less than 10ns, once per cycle.

2948 tbl 04

2948 tbl 02

### **DC Electrical Characteristics**

(Vcc = 5.0V ± 10%)

			IDT71256SA		
Symbol	Parameter	Test Conditions	Min.	Max.	Unit
Lu	Input Leakage Current	Vcc = Max., VIN = GND to Vcc		5	μA
llo	Output Leakage Current	Vcc = Max., $\overline{CS}$ = VH, Vout = GND to Vcc		5	μA
Vol	Output Low Voltage	IOL = 8mA, Vcc = Min.		0.4	V
Vон	Output High Voltage	юн = -4mA, Vcc = Min.	2.4	_	V

2948 tbl 05

### DC Electrical Characteristics<sup>(1)</sup>

(Vcc = 5.0V ± 10%, VLc = 0.2V, VHc = Vcc-0.2V)

Symbol	Parameter	71256SA12	71256SA15	71256SA20	71256SA25	Unit
ICC	<u>Dynamic</u> Operating Current $\overline{CS} \leq VIL$ , Outputs Open, Vcc = Max., f = fMAX <sup>(2)</sup>	160	150	145	145	mA
ISB	Standby Power Supply Current (TTL Level) $\overline{CS} \ge V_{H}$ , Outputs Open, Vcc = Max., f = f <sub>MAX</sub> <sup>(2)</sup>	50	40	40	40	mA
ISB1	$ \begin{array}{l} \underline{Standby \ Power \ Supply \ Current \ (CMOS \ Level)} \\ \overline{CS} \geq V_{HC}, \ Outputs \ Open, \ V_{CC} = Max., \ f = 0^{[2]}, \\ V_{IN} \leq V_{LC} \ or \ V_{IN} \geq V_{HC} \end{array} $	15	15	15	15	mA

2948 tbl 06

NOTES:

1. All values are maximum guaranteed values.

2. fMAX = 1/tRC (all address inputs are cycling at fMAX); f = 0 means no address input lines are changing.

### **AC Test Conditions**

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	3ns
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
AC Test Load	See Figures 1 and 2
	2948 tbl 07



#### (TA = +25°C, f = 1.0MHz, SOJ package)

Symbol	Parameter <sup>(1)</sup>	Conditions	Max.	Unit
CIN	Input Capacitance	Vin = 3dV	7	pF
Cvo	I/O Capacitance	Vout = 3dV	7	pF
				2948 tbl 08

NOTE:

1. This parameter is guaranteed by device characterization, but not production tested.

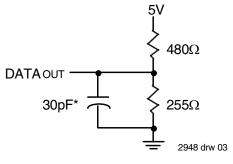


Figure 1. AC Test Load

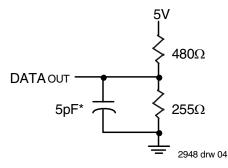


Figure 2. AC Test Load (for tcLz, toLz, tcHz, toHz, toW, and tWHz)

\*Including jig and scope capacitance.

		7125	6SA12	7125	71256SA15		6SA20	71256SA25		
Symbol	Parameter	Min.	Max.	Min.	Max.	Min.	Max.	Min.	i. Max. U	
Read Cycle									-	
tRC	Read Cycle Time	12		15		20		25		ns
taa	Address Access Time		12		15		20		25	ns
tacs	Chip Select Access Time		12		15	_	20		25	ns
tal.z <sup>(1)</sup>	Chip Select to Output in Low-Z	4		4		4		4		ns
tCHZ <sup>(1)</sup>	Chip Select to Output in High-Z	0	6	0	7	0	10	0	11	ns
tOE	Output Enable to Output Valid		6		7		10		11	ns
toLz <sup>(1)</sup>	Output Enable to Output in Low-Z	0		0		0		0		ns
tonz <sup>(1)</sup>	Output Disable to Output in High-Z	0	6	0	6	0	8	0	10	ns
tон	Output Hold from Address Change	3		3		3		3		ns
tPU <sup>(1)</sup>	Chip Select to Power Up Time	0		0		0		0		ns
tpd <sup>(1)</sup>	Chip Deselect to Power Down Time		12		15		20		25	ns
Write C	ycle			•			•		•	
twc	Write Cycle Time	12		15		20		25		ns
taw	Address Valid to End-of-Write	9		10		15		20		ns
tcw	Chip Select to End-of-Write	9		10		15		20		ns
tas	Address Set-up Time	0		0		0		0		ns
twp	Write Pulse Width	8		10		15		20		ns
twr	Write Recovery Time	0		0		0		0		ns
tow	Data Valid to End-of-Write	6		7		11		13		ns
tDH	Data Hold Time	0		0		0		0		ns
tow <sup>(1)</sup>	Output Active from End-of-Write	4		4		4		4		ns
twнz <sup>(1)</sup>	Write Enable to Output in High-Z	0	6	0	6	0	10	0	11	ns

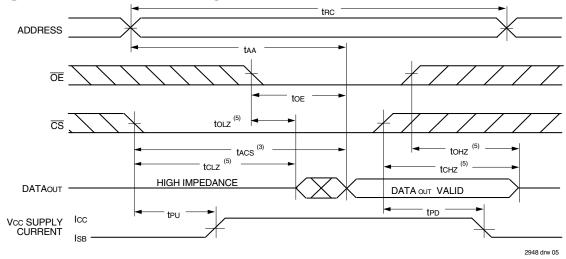
Commercial and Industrial Temperature Ranges

#### NOTE:

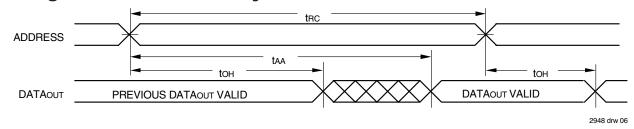
IDT71256SA CMOS Static RAM 256K (32K x 8-Bit)

1. This parameter is guaranteed with the AC Load (Figure 2) by device characterization, but is not production tested.

## Timing Waveform of Read Cycle No. 1<sup>(1)</sup>



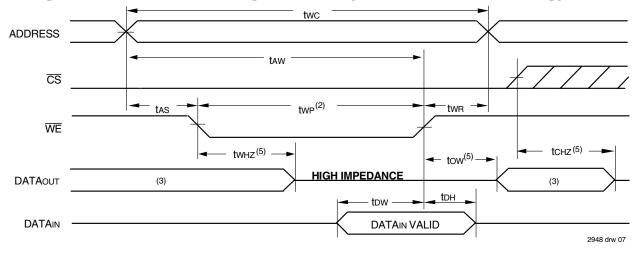
# Timing Waveform of Read Cycle No. 2<sup>(1,2,4)</sup>



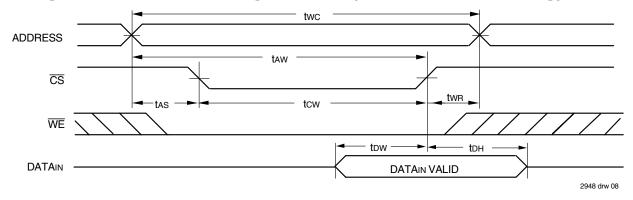
#### NOTES:

- 1.  $\overline{\text{WE}}$  is HIGH for Read Cycle.
- 2. Device is continuously selected,  $\overline{CS}$  is LOW.
- 3. Address must be valid prior to or coincident with the later of CS transition LOW; otherwise tAA is the limiting parameter.
- 4.  $\overline{OE}$  is LOW.
- 5. Transition is measured ±200mV from steady state.

### Timing Waveform of Write Cycle No. 1 (WE Controlled Timing)<sup>(1,2,4)</sup>



### Timing Waveform of Write Cycle No. 2 (CS Controlled Timing)<sup>(1,4)</sup>

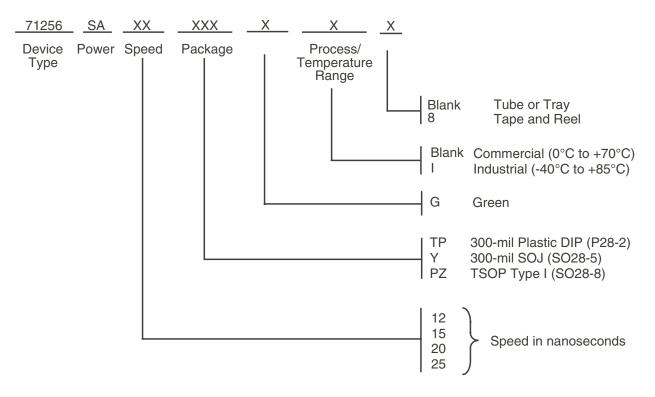


#### NOTES:

- 1. A write occurs during the overlap of a LOW  $\overline{\text{CS}}$  and a LOW  $\overline{\text{WE}}$ .
- 2. OE is continuously HIGH. If during a WE controlled write cycle OE is LOW, twp must be greater than or equal to twHz + tow to allow the I/O drivers to turn off and data to be placed on the bus for the required tow. If OE is HIGH during a WE controlled write cycle, this requirement does not apply and the minimum write pulse is as short as the specified twp.
- 3. During this period, I/O pins are in the output state, and input signals must not be applied.
- 4. If the CS LOW transition occurs simultaneously with or after the WE LOW transition, the outputs remain in a high-impedance state.
- 5. Transition is measured ±200mV from steady state.



### **Ordering Information**



2948 drw 09

#### **Datasheet Document History**

1/7/00		Updated to new format
	Pp. 1, 3, 4, 7	Revised Industrial Temperature range offerings
	Pg. 6	Removed Note No. 1 for Write Cycle diagrams, renumbered footnotes and notes
	Pg. 8	Added Datasheet Document History
08/09/00	-	Not recommended for new designs
02/01/01		Removed "Not recommended for new designs"
09/30/04	Pg. 7	Added "Restricted hazardous substance device" to ordering informations.
02/20/07	Pg. 7	Added TT generation die step to data sheet ordering information.
04/28/11	Pg. 1, 2, 7	Obsoleted 28-pin 600 mil and removed TT generation die step from Ordering information.
	-	Added Tape and Reel to Ordering information and updated description of Restricted hazardous
		substance device to Green.
02/01/01 09/30/04 02/20/07	Pg. 7	Removed "Not recommended for new designs" Added "Restricted hazardous substance device" to ordering informations. Added TT generation die step to data sheet ordering information. Obsoleted 28-pin 600 mil and removed TT generation die step from Ordering information. Added Tape and Reel to Ordering information and updated description of Restricted hazardous



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